

CGHV35120F

120 W, 2.9 - 3.8 GHz, 50 V, GaN HEMT for S-Band Radar Systems

Description

The CGHV35120F is a gallium nitride (GaN) high electron mobility transistor (HEMT) designed specifically with high efficiency, high gain and wide bandwidth capabilities, which makes the CGHV35120F ideal for 2.9 - 3.8 GHz S-Band radar amplifier applications. The transistor is supplied in a ceramic/metal flange package.



PN: 440162 Package Type: CGHV35120F

Typical Performance 3.1 - 3.5 GHz ($T_c = 85$ °C)

Parameter	3.1 GHz	3.2 GHz	3.3 GHz	3.4 GHz	3.5 GHz	Units
Output Power	142	135	132	136	134	W
Gain	13	12.8	12.8	12.9	12.8	dBc
Drain Efficiency	68	66	63	62	62	%

Note: Measured in the CGHV35120F-AMP1 application circuit, under 100 μs pulse width, 10% duty cycle, $P_{IN} = 38.5$ dBm application circuit, under 100 μs pulse width, 10% duty cycle, $P_{IN} = 38.5$ dBm application circuit, under 100 μs pulse width, 10% duty cycle, $P_{IN} = 38.5$ dBm application circuit, under 100 μs pulse width, 10% duty cycle, $P_{IN} = 38.5$ dBm application circuit, under 100 μs pulse width, 10% duty cycle, $P_{IN} = 38.5$ dBm application circuit, under 100 μs pulse width, 10% duty cycle, $P_{IN} = 38.5$ dBm application circuit, under 100 μs pulse width, 10% duty cycle, $P_{IN} = 38.5$ dBm application circuit, under 100 μs pulse width, 10% duty cycle, $P_{IN} = 38.5$ dBm application circuit, under 100 μs pulse width, 10% duty cycle, $P_{IN} = 38.5$ dBm application circuit, under 100 μs pulse width, 10% duty cycle, $P_{IN} = 38.5$ dBm application circuit, under 100 μs pulse width, 10% duty cycle, $P_{IN} = 38.5$ dBm application circuit, $P_{IN} = 38.5$ dBm application circuit cir

Features

- Rated Power = 120 W @ T_{CASE} = 85°C
- Operating Frequency = 2.9 3.8 GHz
- Transient 100 μsec 300 μsec @ 20% Duty Cycle
- 13 dB Power Gain @ T_{CASE} = 85°C

- 62% Typical Drain Efficiency @ T_{CASE} = 85°C
- Input Matched
- <0.3 dB Pulsed Amplitude Droop



Large Signal Models Available for ADS and MWO





Absolute Maximum Ratings (not simultaneous)

Parameter	Symbol	Rating	Units	Conditions
Drain-Source Voltage	V _{DSS}	150	V	0.500
Gate-to-Source Voltage	V _{GS}	-10, +2	V	25°C
Storage Temperature	T _{STG}	-65, +150	°C	
Operating Junction Temperature	T _J	225		
Maximum Forward Gate Current	I _{GMAX}	22.5	mA	2500
Maximum Drain Current ¹	I _{DMAX}	9	Α	25°C
Soldering Temperature ²	T _s	245	°C	
Screw Torque	τ	40	in-oz	
Pulsed Thermal Resistance, Junction to Case ³	R _{eJC}	1.2	°C/W	300 μsec, 20%, 85°C
Case Operating Temperature	T _C	-40, +130	°C	

Notes:

Electrical Characteristics

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions	
DC Characteristics ¹ (T _C = 25°C)							
Gate Threshold Voltage	V _{GS(th)}	-3.8	-3.0	-2.3	V _{DC}	$V_{DS} = 10 \text{ V}, I_{D} = 21.6 \text{ mA}$	
Gate Quiescent Voltage	$V_{GS(Q)}$	_	-2.7	_		$V_{DS} = 48 \text{ V}, I_{D} = 220 \text{ mA}$	
Saturated Drain Current ²	I _{DS}	16.2	20.1	_	Α	$V_{DS} = 6.0 \text{ V}, V_{GS} = 2.0 \text{ V}$	
Drain-Source Breakdown Voltage	V_{BR}	125	_	_	V _{DC}	$V_{GS} = -8 \text{ V}, I_{D} = 21.6 \text{ mA}$	
RF Characteristics ³ ($T_c = 25$ °C, $F_0 =$	3.1 - 3.5 GH	z unles	s other	wise not	ted)		
Output Power at 3.1 GHz	D	135	142	_	W	$V_{DD} = 48 \text{ V}, I_{DQ} = 220 \text{ mA}, P_{IN} = 38.5 \text{ dBm}$	
Output Power at 3.5 GHz	P _{out}	120	134	_	VV		
Output Return Loss	ORL	_	-8	-6			
Input Return Loss	IRL	_	-8	-6	dB		
Gain at 3.1 GHz	_	_	13	_			
Gain at 3.5 GHz	G _P	_	12.8	_			
Drain Efficiency at 3.1 GHz	D	64	68	_	%		
Drain Efficiency at 3.5 GHz	D _E	60	62	_	90		
Amplitude Droop	D	_	-0.3	_	dB		
Output Mismatch Stress	VSWR	_	_	5:1	Ψ	No damage at all phase angles, $V_{DD} = 48 \text{ V}$, $I_{DQ} = 220 \text{ mA}$, $P_{IN} = 38.5 \text{ dBm Pulsed}$	
Dynamic Characteristics	Dynamic Characteristics						
	C _{GS} — 65 —						
Input Capacitance	C _{DS}	_	9.5	_	pF	$V_{DS} = 48 \text{ V}, V_{GS} = -8 \text{ V}, f = 1 \text{ MHz}$	
	C _{GD}	_	0.7	_			

Notes:

² Current limit for long term, reliable operation ² Refer to the Application Note on soldering ³ Measured for the CGHV35120F at P_{DISS} = 80 W

Notes.

1 Measured on wafer prior to packaging

2 Scaled from PCM data

3 Measured in CGHV35120-AMP. Pulse Width = 100 μs, Duty Cycle = 10%



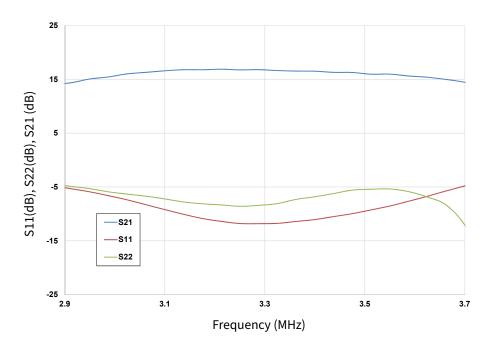


Figure 1. CGHV35120F Typical S Parameters Measured in CGHV35120F-AMP1 $V_{DD} = 48 \text{ V}, I_{DO} = 220 \text{ mA}, T_{CASE} = 25 ^{\circ}\text{C}$

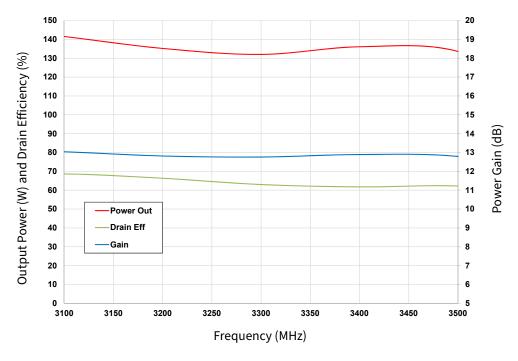


Figure 2. CGHV35120F Typical RF Results Measured in CGHV35120F-AMP1 V_{DD} = 48 V, I_{DO} = 220 mA, T_{PLATE} = 85°C, Pulse Width = 100 μ s, Duty Cycle = 10%



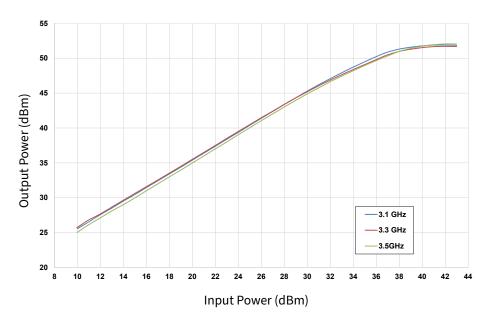


Figure 3. CGHV35120F Output Power vs Input Power Measured in CGHV35120F-AMP1 V_{DD} = 48 V, I_{DQ} = 220 mA, T_{PLATE} = 85°C, Pulse Width = 100 μ s, Duty Cycle = 10%

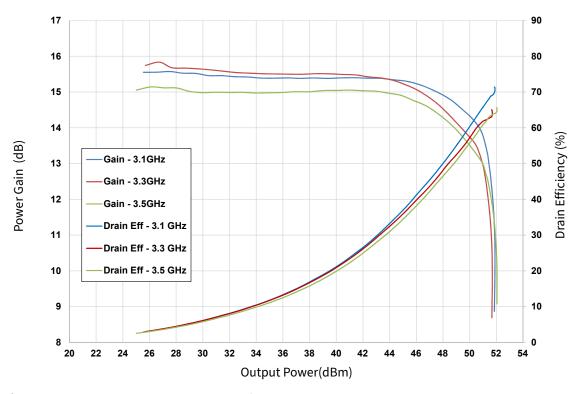


Figure 4. CGHV35120F Gain and Drain Efficiency vs Output Power Measured in CGHV35120F-AMP1 V_{DD} = 48 V, I_{DQ} = 220 mA, T_{PLATE} = 85°C, Pulse Width = 100 μ s, Duty Cycle = 10%



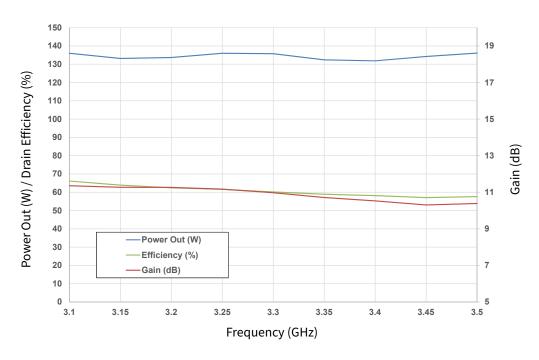


Figure 5. CGHV35120F Power Out/Drain Efficiency vs Frequency Measured in CGHV35120F-AMP1 $V_{DD} = 48 \text{ V}$, P_{SAT} where IG > 0, Pulse Width = 1msec, Duty Cycle = 20%

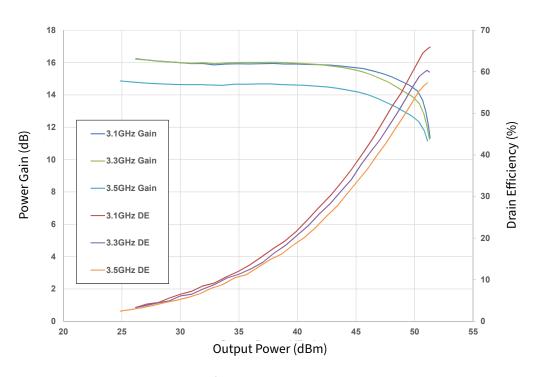


Figure 6. CGHV35120F Gain and Drain Efficiency vs Output Power Measured in CGHV35120F-AMP1 V_{DD} = 48 V, I_{DQ} = 220 mA, T_{PLATE} = 25°C, Pulse Width = 1msec, Duty Cycle = 20%



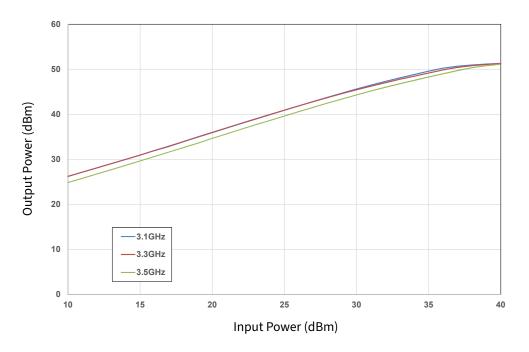


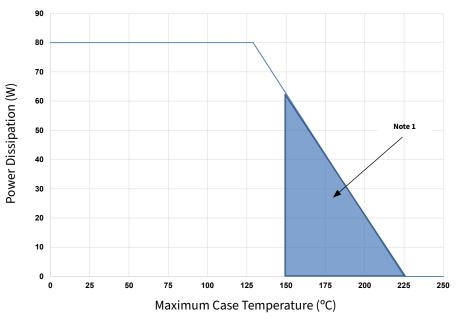
Figure 7. CGHV35120F Output Power vs Input Power Measured in CGHV35120F-AMP1 $V_{DD} = 48 \text{ V}$, $I_{DO} = 220 \text{ mA}$, $T_{PLATE} = 25 ^{\circ}\text{C}$, Pulse Width = 1msec, Duty Cycle = 20%

Electrostatic Discharge (ESD) Classifications

Parameter	Symbol	Class	Classification Level	Test Methodology
Human Body Model	НВМ	1A	ANSI/ESDA/JEDEC JS-001 Table 3	JEDEC JESD22 A114-D
Charge Device Model	CDM	0CB	ANSI/ESDA/JEDEC JS-002 Table 3	JEDEC JESD22 C101-C



CGHV35120F Power Dissipation De-rating Curve



Note: Area exceeds Maximum Case Temperature (See Page 2)

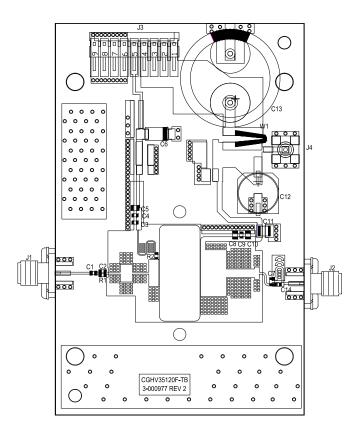
CGHV35120F Bill of Materials

Designator	Description	Qty
R1	RES, 511 ohms, +/- 1%, 1/16W, 0603	1
R2	RES, 5.1, ohm, +/- 1%, 1/16W, 0603	1
C8	CAP, 10pF, +/- 1%, 250V, 0805, ATC	2
C2	CAP, 6.8pF, +/- 0.25 pF, 250V, 0603, ATC	1
C1, C3	CAP, 10.0pF, +/-5%, 250V, 0603, ATC	2
C4, C9	CAP, 470pF, 5%, 100V, 0603, X7R	2
C5, C10	CAP, 33000pF, 0805,100V, X7R	2
C6	CAP, 10μF, 16V, TANTALUM	1
C7	CAP, 6.8pF, +/- 1%, 250V, 0805, ATC	1
C11	CAP, 1.0μF, 100V, 10%, X7R, 1210	1
C12	CAP, 33 μF, 20%, G CASE	1
C13	CAP, 3300 μF, +/-20%, 100V, ELECTROLYTIC	1
C14	CAP, 0.4pF, +/-0.1pF, 0603, ATC	1
J1, J2	CONN, SMA, PANEL MOUNT JACK, FLANGE, 4-HOLE, BLUNT POST, 20MIL	2
J3	HEADER RT>PLZ .1CEN LK 9POS	1
J4	CONNECTOR; SMB, Straight, JACK, SMD	1
W1	CABLE, 18 AWG, 4.2	1
	PCB, RO4350, 10 MIL THK, CGHV35120F	1
Q1	CGHV35120F	1

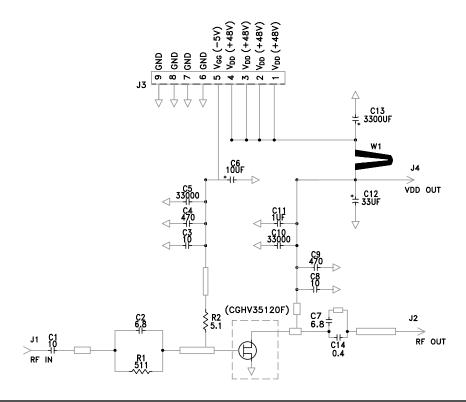
For further information and support please visit: Rev. 1.0, 2022-8-3



CGHV35120F-AMP1 Application Circuit Outline

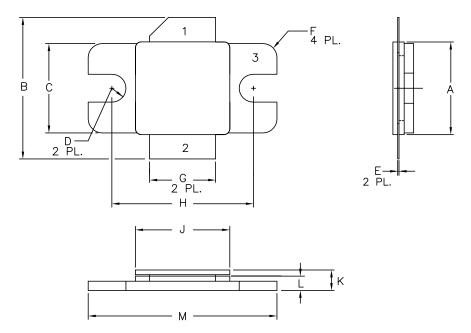


CGHV35120F-AMP1 Application Circuit Schematic





Product Dimensions CGHV35120F (Package Type — 440162)



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
- LID MAY BE MISALIGNED TO THE BODY
 OF THE PACKAGE BY A MAXIMUM OF 0.008" IN
 ANY DIRECTION.

	INCHES		MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	.395	.405	10.03	10.29
В	.580	.620	14.73	15.75
С	.380	.390	9.65	9.91
D	.055	.065	1.40	1.65
Е	.004	.006	0.10	0.15
F	.055	.065	1.40	1.65
G	.275	.285	6.99	7.24
Н	.595	.605	15.11	15.37
J	.395	.405	10.03	10.29
K	.129	.149	3.28	3.78
L	.053	.067	1.35	1.70
М	.795	.805	20.19	20.45

PIN 1. GATE PIN 2. DRAIN PIN 3. SOURCE



Part Number System

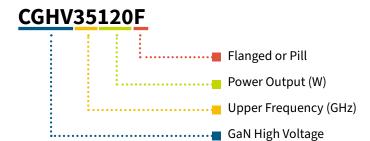


Table 1.

Parameter	Value	Units
Upper Frequency ¹	3.8	GHz
Power Output	120	W
Package	Flange	_

Table 2.

Character Code	Code Value
А	0
В	1
С	2
D	3
E	4
F	5
G	6
Н	7
J	8
K	9
Examples:	1A = 10.0 GHz 2H = 27.0 GHz

Note: ¹ Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.



Product Ordering Information

Order Number	Description	Unit of Measure	Image
CGHV35120F	GaN HEMT	Each	CONTROLL
CGHV35120F-AMP1	3.1 - 3.5 GHz test board with GaN HEMT installed	Each	



Notes & Disclaimer

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